

## MC14015B

### Dual 4-Bit Static Shift Register

The MC14015B dual 4-bit static shift register is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. It consists of two identical, independent 4-state serial-input/parallel-output registers. Each register has independent Clock and Reset inputs with a single serial Data input. The register states are type D master-slave flip-flops. Data is shifted from one stage to the next during the positive-going clock transition. Each register can be cleared when a high level is applied on the Reset line. These complementary MOS shift registers find primary use in buffer storage and serial-to-parallel conversion where low power dissipation and/or noise immunity is desired.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Edge-Clocked Flip-Flop Design —  
 Logic state is retained indefinitely with clock level either high or low; information is transferred to the output only on the positive going edge of the clock pulse.
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range.

#### MAXIMUM RATINGS\* (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage	- 0.5 to + 18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	- 0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient), per Pin	± 10	mA
P <sub>D</sub>	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
T <sub>L</sub>	Lead Temperature (8-Second Soldering)	260	°C

\* Maximum Ratings are those values beyond which damage to the device may occur.

† Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

Ceramic "L" Packages: - 12 mW/°C From 100°C To 125°C

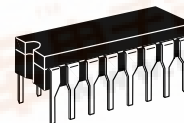
#### TRUTH TABLE

C	D	R	Q <sub>0</sub>	Q <sub>n</sub>
✓	0	0	0	Q <sub>n-1</sub>
✓	1	0	1	Q <sub>n-1</sub>
~	X	0	No Change	No Change
X	X	1	0	0

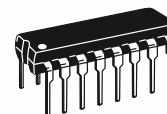
X = Don't Care

Q<sub>n</sub> = Q<sub>0</sub>, Q<sub>1</sub>, Q<sub>2</sub>, or Q<sub>3</sub>, as applicable.

Q<sub>n-1</sub> = Output of prior stage.



**L SUFFIX**  
 CERAMIC  
 CASE 620



**P SUFFIX**  
 PLASTIC  
 CASE 648



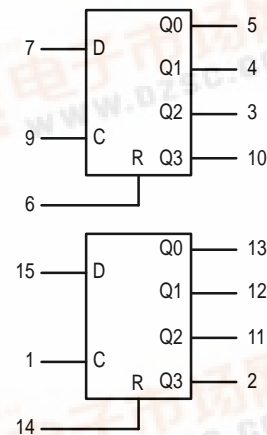
**D SUFFIX**  
 SOIC  
 CASE 751B

#### ORDERING INFORMATION

MC14XXXBCP Plastic  
 MC14XXXBCL Ceramic  
 MC14XXXBD SOIC

T<sub>A</sub> = - 55° to 125°C for all packages.

#### BLOCK DIAGRAM



V<sub>DD</sub> = PIN 16  
 V<sub>SS</sub> = PIN 8

**ELECTRICAL CHARACTERISTICS** (Voltages Referenced to  $V_{SS}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	- 55 °C		25 °C			125 °C		Unit	
			Min	Max	Min	Typ #	Max	Min	Max		
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	$V_{OL}$	5.0	—	0.05	—	0	0.05	—	0.05	Vdc	
		10	—	0.05	—	0	0.05	—	0.05		
15		—	0.05	—	0	0.05	—	0.05			
$V_{in} = 0$ or $V_{DD}$ "1" Level	$V_{OH}$	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc	
10		9.95	—	9.95	10	—	9.95	—			
15		14.95	—	14.95	15	—	14.95	—			
Input Voltage "0" Level ( $V_O = 4.5$ or $.05$ Vdc) ( $V_O = 9.0$ or $1.0$ Vdc) ( $V_O = 13.5$ or $1.5$ Vdc)	$V_{IL}$	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc	
		10	—	3.0	—	4.50	3.0	—	3.0		
15		—	4.0	—	6.75	4.0	—	4.0			
( $V_O = 0.5$ or $4.5$ Vdc) "1" Level ( $V_O = 1.0$ or $9.0$ Vdc) ( $V_O = 1.5$ or $13.5$ Vdc)	$V_{IH}$	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc	
10		7.0	—	7.0	5.50	—	7.0	—			
15		11	—	11	8.25	—	11	—			
Output Drive Current ( $V_{OH} = 2.5$ Vdc) ( $V_{OH} = 4.6$ Vdc) ( $V_{OH} = 9.5$ Vdc) ( $V_{OH} = 13.5$ Vdc)	Source	$I_{OH}$	5.0	- 3.0	—	- 2.4	- 4.2	—	- 1.7	—	mAdc
		5.0	- 0.64	—	- 0.51	- 0.88	—	- 0.36	—		
10		- 1.6	—	- 1.3	- 2.25	—	- 0.9	—			
15		- 4.2	—	- 3.4	- 8.8	—	- 2.4	—			
( $V_{OL} = 0.4$ Vdc) ( $V_{OL} = 0.5$ Vdc) ( $V_{OL} = 1.5$ Vdc)	Sink	$I_{OL}$	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
10		1.6	—	1.3	2.25	—	0.9	—			
15		4.2	—	3.4	8.8	—	2.4	—			
Input Current	$I_{in}$	15	—	$\pm 0.1$	—	$\pm 0.00001$	$\pm 0.1$	—	$\pm 1.0$	$\mu$ Adc	
Input Capacitance ( $V_{in} = 0$ )	$C_{in}$	—	—	—	—	5.0	7.5	—	—	pF	
Quiescent Current (Per Package)	$I_{DD}$	5.0	—	5.0	—	0.005	5.0	—	150	$\mu$ Adc	
		10	—	10	—	0.010	10	—	300		
		15	—	20	—	0.015	20	—	600		
Total Supply Current**† (Dynamic plus Quiescent, Per Package) ( $C_L = 50$ pF on all outputs, all buffers switching)	$I_T$	5.0	$I_T = (1.2 \mu\text{A/kHz})f + I_{DD}$							$\mu$ Adc	
10	$I_T = (2.4 \mu\text{A/kHz})f + I_{DD}$										
15	$I_T = (3.6 \mu\text{A/kHz})f + I_{DD}$										

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

\*\*The formulas given are for the typical characteristics only at 25 °C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where:  $I_T$  is in  $\mu\text{A}$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts,  $f$  in kHz is input frequency, and  $k = 0.002$ .

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

**PIN ASSIGNMENT**

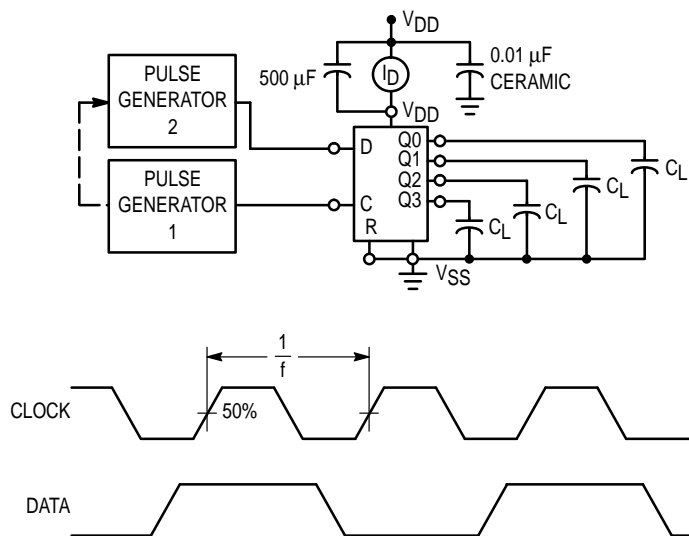
$C_B$	1	16	$V_{DD}$
$Q3_B$	2	15	$D_B$
$Q2_A$	3	14	$R_B$
$Q1_A$	4	13	$Q0_B$
$Q0_A$	5	12	$Q1_B$
$R_A$	6	11	$Q2_B$
$D_A$	7	10	$Q3_A$
$V_{SS}$	8	9	$C_A$

**SWITCHING CHARACTERISTICS\*** ( $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$ )

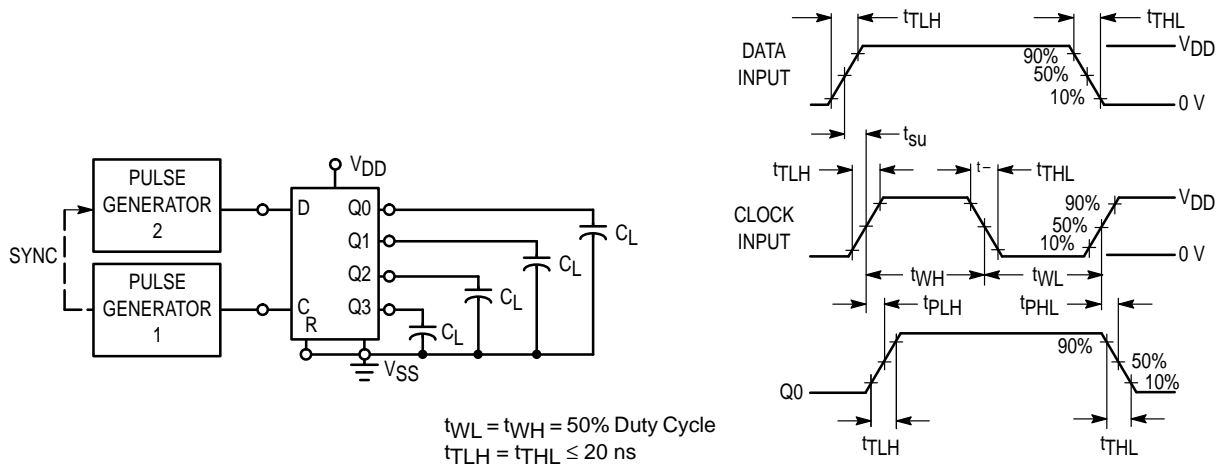
Characteristic	Symbol	V <sub>DD</sub>	Min	Typ #	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TLH}, t_{THL}$	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time Clock, Data to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 225 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 92 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 65 \text{ ns}$ Reset to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 375 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 147 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 95 \text{ ns}$	$t_{PLH}, t_{PHL}$	5.0 10 15	— — —	310 125 90	750 250 170	ns
Clock Pulse Width	$t_{WH}$	5.0 10 15	400 175 135	185 85 55	— — —	ns
Clock Pulse Frequency	$f_{cl}$	5.0 10 15	— — —	2.0 6.0 7.5	1.5 3.0 3.75	MHz
Clock Pulse Rise and Fall Times	$t_{TLH}, t_{THL}$	5.0 10 15	— — —	— — —	15 5 4	$\mu\text{s}$
Reset Pulse Width	$t_{WH}$	5.0 10 15	400 160 120	200 80 60	— — —	ns
Setup Time	$t_{su}$	5.0 10 15	350 100 75	100 50 40	— — —	ns

\* The formulas given are for typical characteristics only at 25°C.

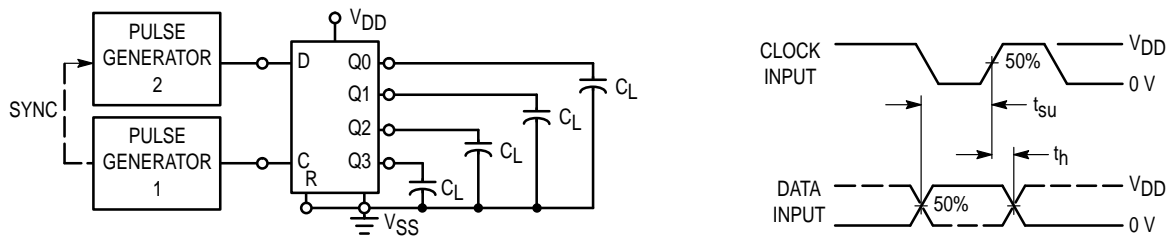
#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



**Figure 1. Power Dissipation Test Circuit and Waveform**

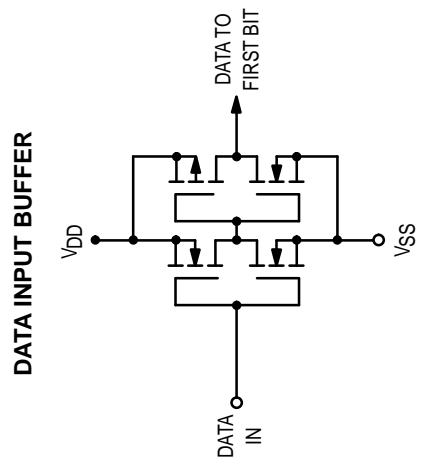
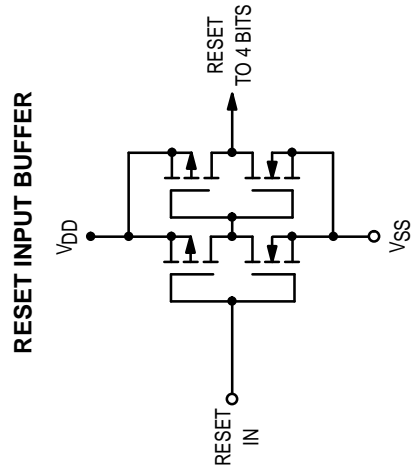
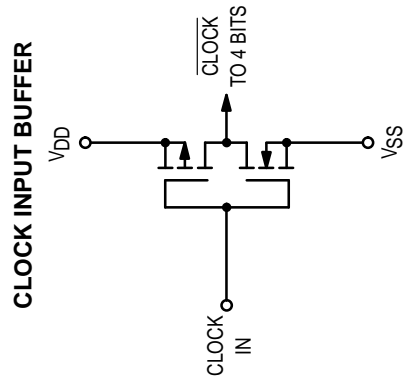
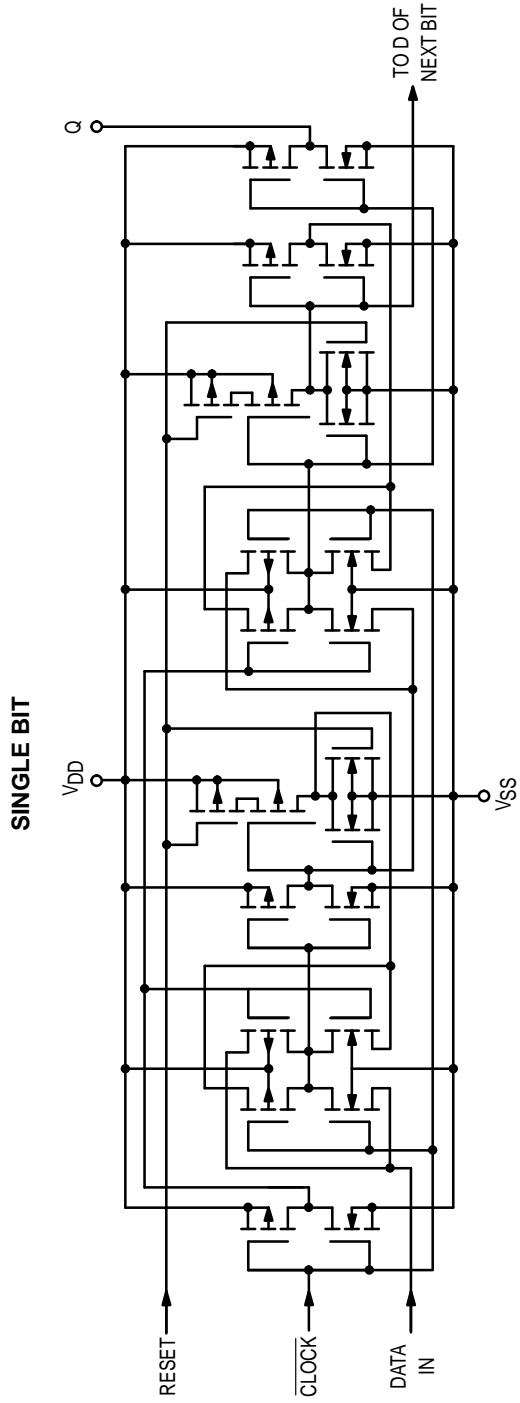


**Figure 2. Switching Test Circuit and Waveforms**



**Figure 3. Setup and Hold Time Test Circuit and Waveforms**

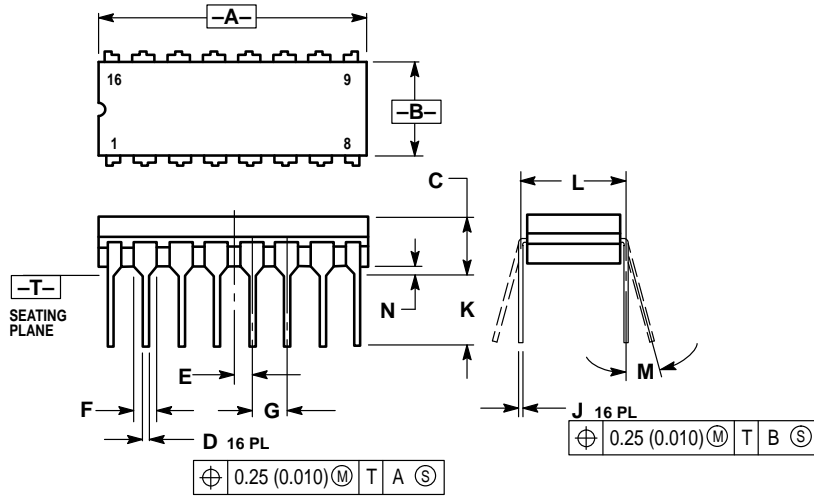
# CIRCUIT SCHEMATICS





## OUTLINE DIMENSIONS

### L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V

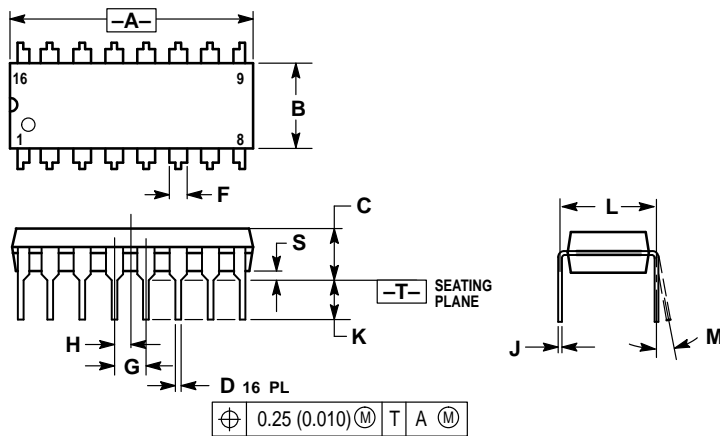


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

### P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



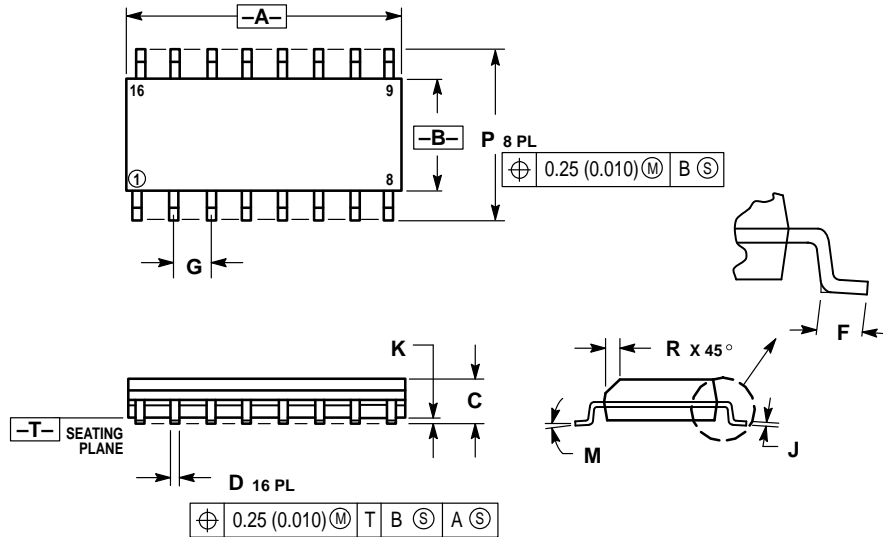
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

## OUTLINE DIMENSIONS


### D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° 7°		0° 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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